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# **FDA24N50**

# May 2014

# N-Channel UniFET<sup>TM</sup> MOSFET 500 V, 24 A, 190 m $\Omega$

#### **Features**

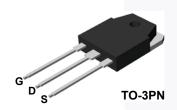
- $R_{DS(on)}$  = 160 m $\Omega$  (Typ.) @  $V_{GS}$  = 10 V,  $I_D$  = 12 A
- Low Gate Charge (Typ. 65 nC)
- Low C<sub>rss</sub> (Typ. 35 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

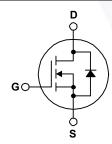
## **Applications**

- PDP TV
- · Uninterruptible Power Supply
- · AC-DC Power Supply

# **Description**

UniFET<sup>TM</sup> MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.





# **MOSFET Maximum Ratings** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol		Parameter		FDA24N50	Unit
V <sub>DSS</sub>	Drain to Source Voltage			500	V
V <sub>GSS</sub>	Gate to Source Voltage	Gate to Source Voltage			V
	Drain Current	- Continuous (T <sub>C</sub> = 25°C)		24	А
ID	Diain Current	- Continuous (T <sub>C</sub> = 100°C)		14	A
I <sub>DM</sub>	Drain Current	- Pulsed (I	- Pulsed (Note 1)		Α
E <sub>AS</sub>	Single Pulsed Avalanche	Energy (I	Note 2)	1872	mJ
I <sub>AR</sub>	Avalanche Current	(I	Note 1)	24	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1		Note 1)	27	mJ
dv/dt	Peak Diode Recovery dv/	/dt (I	Note 3)	4.5	V/ns
D	Dawar Diagination	(T <sub>C</sub> = 25°C)		270	W
$P_{D}$	Power Dissipation	- Derate Above 25°C		2.2	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Te	emperature Range		-55 to +150	οС
TL	Maximum Lead Tempera	ture for Soldering, 1/8" from Case for 5 Secon	ds	300	°C

#### **Thermal Characteristics**

Symbol	Parameter FDA24N50		Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.46	°C/W
R <sub>e,IA</sub>	Thermal Resistance, Junction to Ambient, Max.	40	

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDA24N50	FDA24N50	TO-3PN	Tube	N/A	N/A	30 units

# **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V, T_J = 25^{\circ} C$	500	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C	-	0.66	-	V/°C
1	Zero Gate Voltage Drain Current	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μА
IDSS	Zero Gate Voltage Drain Current	$V_{DS} = 400 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	10	μΑ
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	3.0	-	5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A	-	0.16	0.19	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 12 A	ı	28	1	S

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V - 25 V V - 0 V		-	3120	4150	pF
Coss	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz		-	460	615	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12		-\	35	52	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 24 A,		- \	65	85	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V		- 1	18	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		(Note 4)	-	26	-	nC

## **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		-	47	104	ns
t <sub>r</sub>		$V_{DD} = 250 \text{ V}, I_D = 24 \text{ A},$	-	108	226	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_G$ = 25 $\Omega$	-	164	338	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	-	86	182	ns

#### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diod	Maximum Continuous Drain to Source Diode Forward Current		-	24	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Fo	Maximum Pulsed Drain to Source Diode Forward Current		-	96	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 24 A	-	-	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 24 A,	-	540	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt = 100 A/μs	-	8.1	_	μС

#### Notes:

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. L = 6.5 mH, I<sub>AS</sub> = 24 A, V<sub>DD</sub> = 50 V, R<sub>G</sub> = 25  $\Omega$ , starting T<sub>J</sub> = 25°C.
- 3. I\_{SD}  $\leq$  24 A, di/dt  $\leq$  200 A/µs, V\_{DD}  $\leq$  BV\_DSS, starting T\_J = 25°C.
- Essentially independent of operating temperature typical characteristics.

### **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

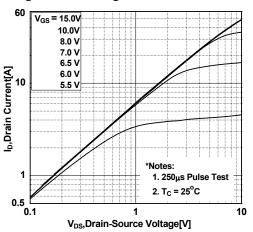


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

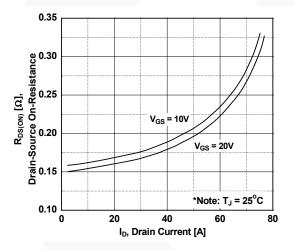
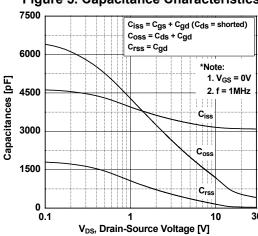


Figure 5. Capacitance Characteristics



**Figure 2. Transfer Characteristics** 

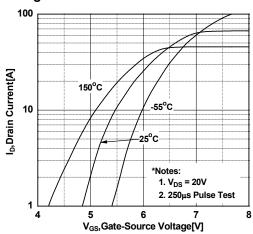
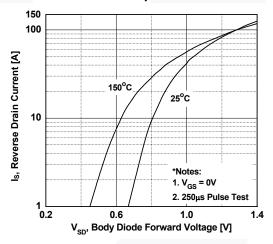
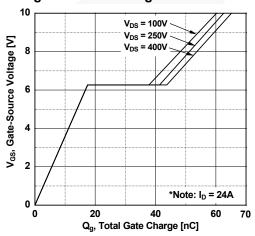


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



**Figure 6. Gate Charge Characteristics** 



# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

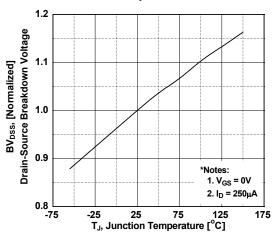


Figure 8. On-Resistance Variation vs. Temperature

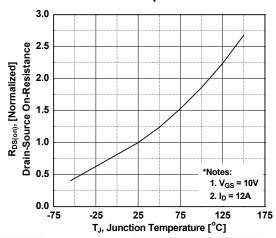


Figure 9. Maximum Safe Operating Area

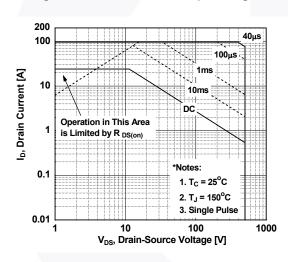


Figure 10. Maximum Drain Current vs. Case Temperature

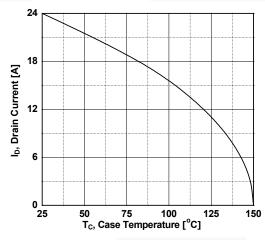
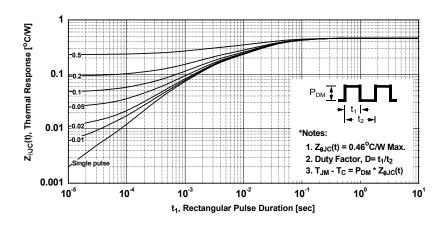


Figure 11. Transient Thermal Response Curve



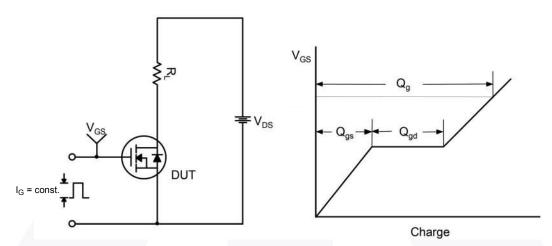


Figure 12. Gate Charge Test Circuit & Waveform

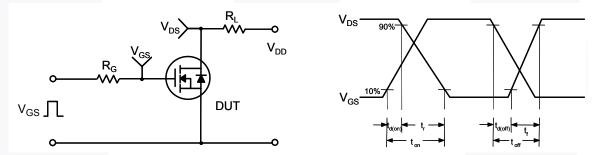


Figure 13. Resistive Switching Test Circuit & Waveforms

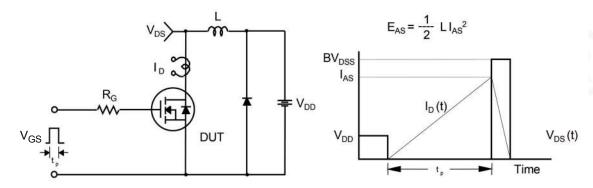


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

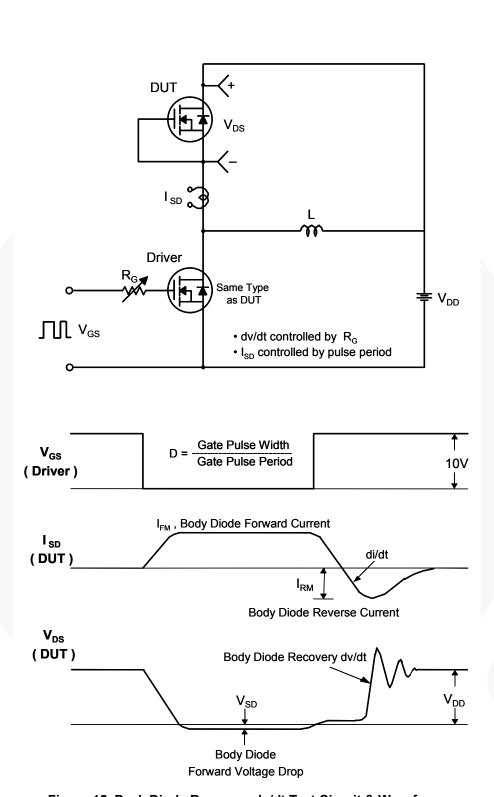


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

#### **Mechanical Dimensions**

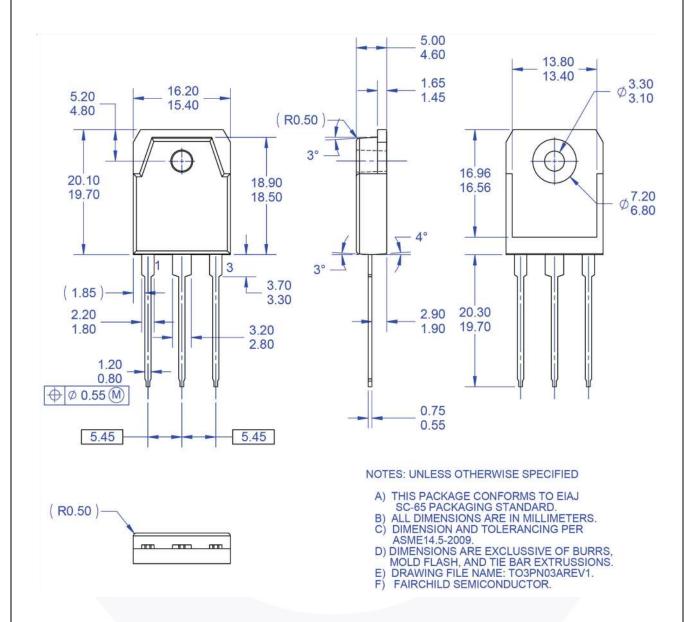


Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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